COMBINED DECLARATION AND POWER OF ATTORNEY FOR PATENT APPLICATION

As a below-named inventor, I hereby declare that: My residence, post office and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below), or an original, first and joint inventor (if plural names are listed below), of the subject matter which is claimed and for which a patent is sought on the invention entitled:

DIRECT CHIP ATTACH STRUCTURE AND METHOD the specification of which is attached hereto unless the following box is checked: Application was filed on as Application No. and was amended on I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above. I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, §1.56. I hereby claim foreign priority benefits under Title 35, United States Code, § 119(a)-(d) of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed. Prior Foreign Application(s) Priority Claimed ___ Yes ___ No (Country) (Filed) (Number) I hereby claim the benefit under Title 35, United States Code, § 119(e) of any United States provisional application(s) listed below. Application No. File date

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application.

DECLARATION

(Application Number) (Filing Date) (Status - patented, pending, abandoned):
I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the U.S. Patent and Trademark Office connected therewith:
James J. Stipanuk, Reg. #44,358 Address all telephone calls to Mr. James J. Stipanuk at (602) 244-4885; facsimile Number (602) 244-3169.
Address all correspondence to James J. Stipanuk, Semiconductor Components Industries, L.L.C., Patent Administration Dept - MD/A700, P.O. Box 62890, Phoenix, Arizona 85082-2890.
I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.
FULL NAME OF FIRST INVENTOR: James Knapp INVENTOR SIGNATURE: Lines Date: 24 June 2003 RESIDENCE: 2975 EAST ROBIN LANE GILBERT, AZ USA 85296 CITIZENSHIP: USA POST OFFICE ADDRESS: Same as above
FULL NAME OF SECOND INVENTOR (if any): Kok Yang Lau INVENTOR SIGNATURE: DATE: 18 June 1003 RESIDENCE: 3491 Simpang Bekoh, Asahan Melaka, Malyasia 77100
CITIZENSHIP: MALAYSIAN POST OFFICE ADDRESS: Same as above.
FULL NAME OF THIRD INVENTOR (if any): Beng Lian Lim INVENTOR SIGNATURE: DATE: Presidence: 3034, TAMAN SEREMBAN BARU,

DECLARATION

FULL NAME OF Fourth INVENTOR (if any): Guan Keng Quah

INVENTOR SIGNATURE: Grah Kentsman DATE: 6.23,03

RESIDENCE: 1843 E Catamaran Dr,

Gilbert, ARIZONA, USA 85234

CITIZENSHIP: USA

POST OFFICE ADDRESS: Same as above